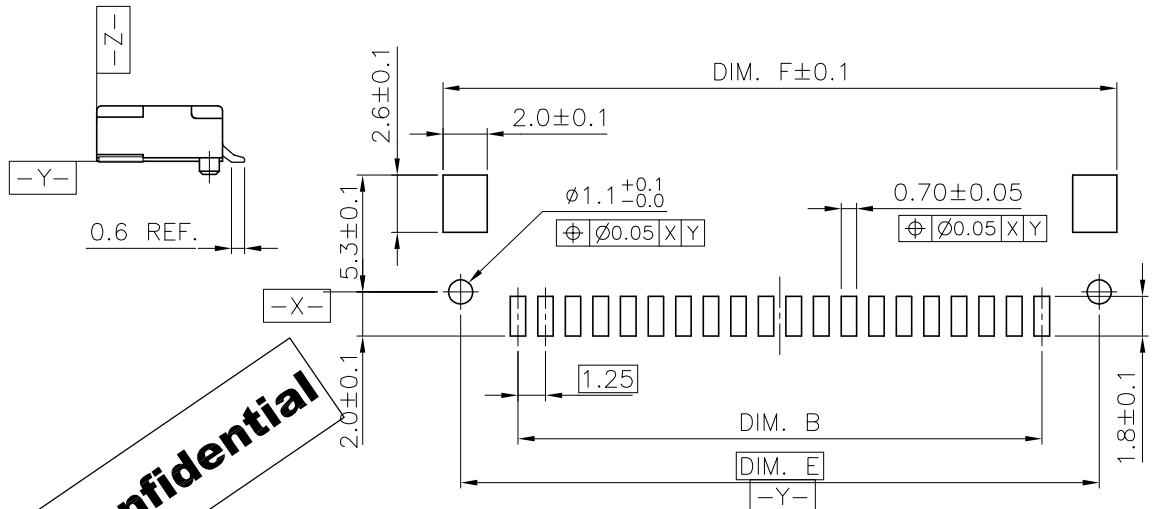
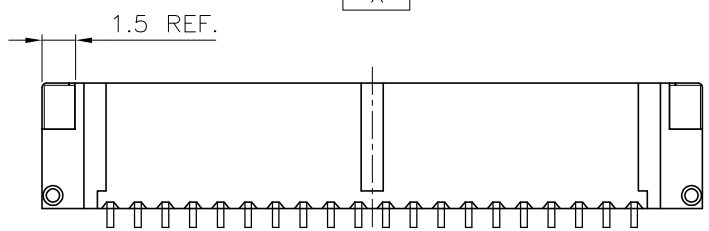
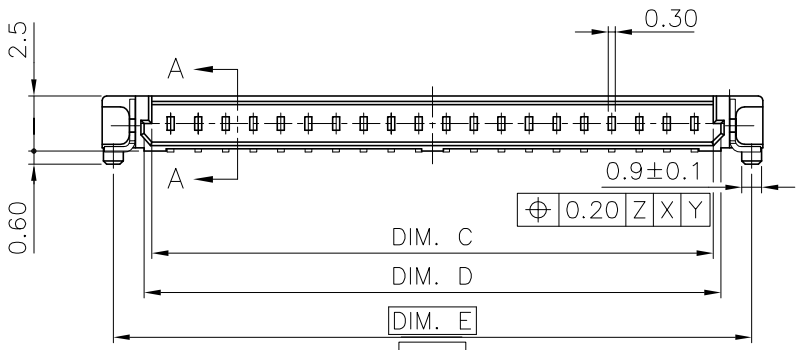
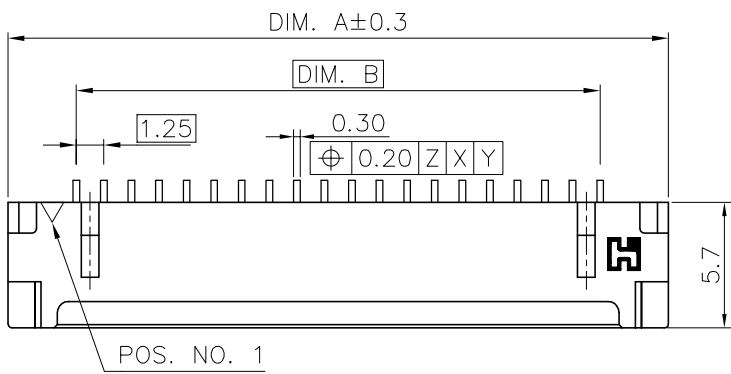
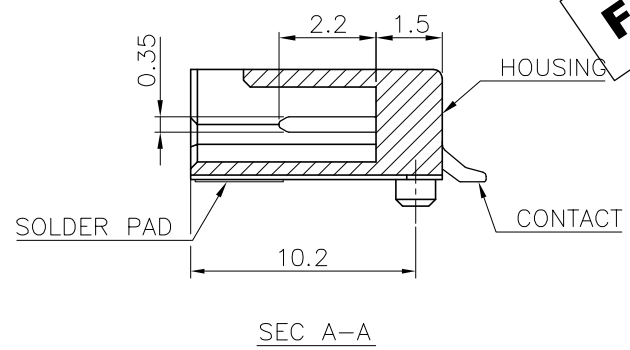


REV.	ECN. NO.	APPD.
A	HC991361	Dick Lee 4/28 '99
B	HC993876	Dick Lee 12/23 '99
C	MC003075	Dick Lee 9/2'2K
D	HC047513	Ady Zhou 8/3,04
E	HC052482	Ady Zhou 3/31,05

- NOTES: UNLESS OTHERWISE SPECIFIED
- ALL DIMENSIONS ARE IN MILLIMETER.
 - MATERIAL:
CONTACT: PH/BR
HOUSING: LCP, THERMOPLASTIC, UL 94V-0 RATED,
COLOR IN IVORY
SOLDER PAD: BRASS
 - CONTACT FINISH:
NICKEL PLATING OVER ALL AT 50 u" MIN..
SOLDER AREA: TIN/LEAD OR TIN PLATING WITH LEAD FREE 100 u" MIN.
CONTACT AREA: TIN/LEAD OR TIN PLATING WITH LEAD FREE 100 u" MIN.
 - SOLDER PAD FINISH:
NICKEL PLATING OVER ALL AT 50 u" MIN..
TIN/LEAD OR TIN PLATING WITH LEAD FREE OVER NICKEL 100 u" MIN.



RECOMMENDED P.C.B. LAYOUT



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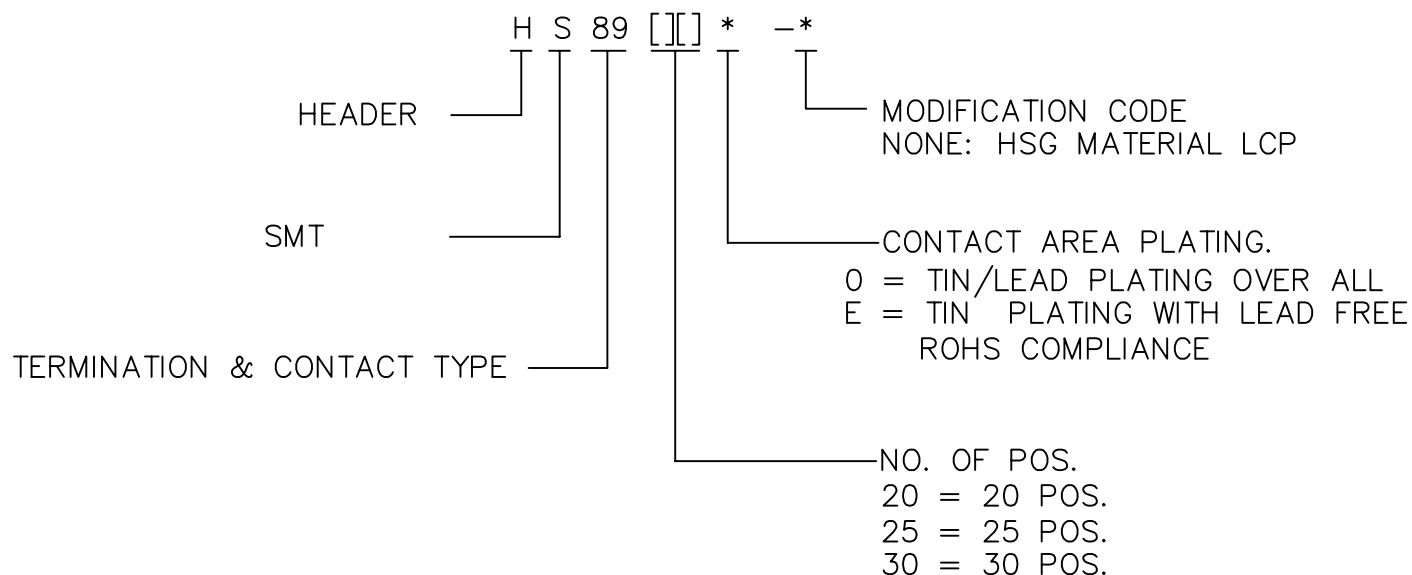
HS8930*-*	30	42.45	36.25	37.95	38.65	41.45	43.05
HS8925*-*	25	36.20	30.00	31.70	32.40	35.20	36.80
HS8920*-*	20	29.95	23.75	25.45	26.15	28.95	30.55
PRODUCT NO.	NO. OF POS.	DIM. A	DIM. B	DIM. C	DIM. D	DIM. E	DIM. F

X.±	X°±	UNITS	mm	NAME (INTENDED USE)	FOXCONN HON HAI PRECISION IND. CO., LTD. TAIPEI, TAIWAN, R.O.C.
.X± 0.3	.X°±	MAT'L		LVDS CONN.	
.XX± 0.2	.XX°±	FINISH		PART NO. (INTENDED USE) HS89 SERIES	TITLE: CUSTOMER DRAWING
.XXX±	.XXX°±	Q'TY		APPD: Jake W.Y	DWG NO.: 307-0000-341
THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF HON HAI PRECISION IND. CO., LTD. AND SHALL NOT BE REPRODUCED, COPIED OR USED IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF HON HAI PRECISION IND. CO., LTD.				CHKD: D.J.Chen	
				DR: Nick Yu 11/19'07	

ITEM	DESC.	Q'TY	MATERIAL	TREATMENT	REMARK
1	HOUSING	1	LCP, THERMO-PLASTIC,UL 94V-0	MOLDED IVORY	
2	CONTACT	SEE NOTE BELOW	PH/BR	A) NICKEL PLATING OVER ALL THICKNESS : 50 u" MIN. B) TIN/LEAD OR TIN WITH LEAD FREE PLATING OVER NICKEL. THICKNESS : 100 u" MIN	
3	PAD	2	BRASS	A) NICKEL PLATING OVER ALL THICKNESS : 50 u" MIN. B) TIN/LEAD OR TIN WITH LEAD FREE PLATING OVER NICKEL. THICKNESS : 100 u" MIN	

NOTE :

1.PRODUCT NO. MATRIX



2. HARMFUL MATERIAL CONTROL PLEASE FOLLOW DOC. No. "EPI12"

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C	HC047557	Ady Zhou 8/3,04
B	MC994434	Dick 12/23,99
A	HC991361	Dick LEE 4/28,99
REV.	ECN NO	APPD.

APPD. : Yusan	TITLE : MATERIAL 1.25mm PITCH
CHKD. : D.J.Chen	PROD. SERIES : HS89 SERIES
DR. : Nick Yu 11/15'07	DWG. NO : 307-0000-855
	REV. : CX1 SHEET : 1/1

SPECIFICATIONS :

1. MATERIAL :

1-1. HOUSING :

LCP, THERMOPLASTIC , UL94V-0 , COLOR IVORY

1-2. CONTACT :

PH/BR,NICKEL PLATING OVER ALL,THICKNESS 50u" MIN.,
TINWITH LEAD FREE PLATING OVER ALL,THICKNESS 100u"MIN.

1-3. SOLDER PAD :

BRASS,NICKEL PLATING OVER ALL,THICKNESS 50u" MIN.,
TINWITH LEAD FREE PLATING OVER ALL,THICKNESS 100u"MIN.

2. PERFORMANCE :

2-1. VOLTAGE RATING : 250 VAC

2-2. CURRENT RATING : 1.0 Amps MAX. PER CONTACT

2-3. OPERATING TEMPERATURE : -55°C TO +105°C

3. ELECTRICAL :

3-1. LOW LEVEL CONTACT RESISTANCE(DRY CIRCUIT) : 30 MILLIOHMS MAX. INITIAL

3-2. DIELECTRIC WITHSTANDING VOLTAGE : 250 VAC /1 MIN

3-3. INSULATION RESISTANCE : 1000 MEGAOHMS MIN. INITIAL

4. MECHANICAL:

4-1. RETENTION FORCE: 0.454 kgf MIN.

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TAIPEI, TAIWAN, R.O.C.

APPD. : Yusan	TITLE :SPECIFICATION LVDS CONN.1.25mm SMT TYPE	
CHKD. : D.J.Chen	PROD. SERIES : HS89 SERIES	
DR. : Nick Yu 11/15'07	DWG. NO : 307-0300-179	
	REV. : AX1	SHEET : 1/1

A	HC991361	Dick Lee 4/28 '99
REV.	ECN NO	APPD.